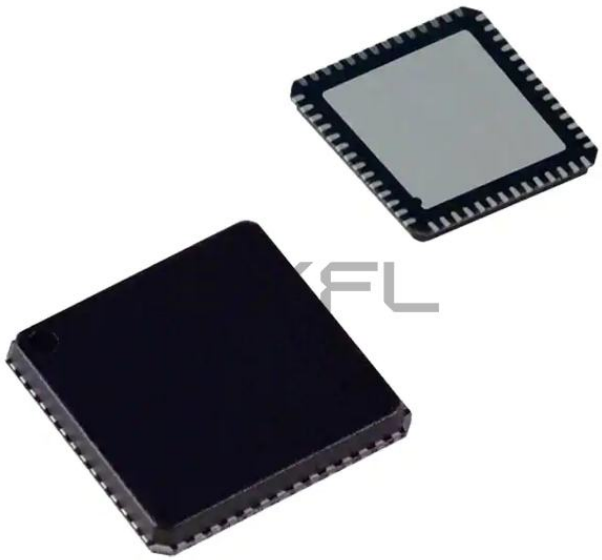

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8052
Core Size	8-Bit
Speed	16.78MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	DMA, PSM, PWM, Temp Sensor, WDT
Number of I/O	32
Program Memory Size	62KB (62K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.25K x 8
Voltage - Supply (Vcc/Vdd)	4.75V ~ 5.25V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	56-VFQFN Exposed Pad, CSP
Supplier Device Package	56-LFCSP-VQ (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/aduc843bcp62z-5

[1] Temperature Range –40°C to +85°C.
[2] ADC linearity is guaranteed during normal MicroConverter core operation.
[3] ADC LSB size = $V_{REF}/2^{12}$, that is, for internal V_{REF} = 2.5 V, 1 LSB = 610 µV, and for external V_{REF} = 1 V, 1 LSB = 244 µV.
[4] These numbers are not production tested but are supported by design and/or characterization data on production release.
[5] Offset and gain error and offset and gain error match are measured after factory calibration.
[6] Based on external ADC system components, the user may need to execute a system calibration to remove additional external channel errors to achieve these specifications.
[7] SNR calculation includes distortion and noise components.
[8] Channel-to-channel crosstalk is measured on adjacent channels.
[9] The temperature monitor gives a measure of the die temperature directly; air temperature can be inferred from this result.
[10] DAC linearity is calculated using:
Reduced code range of 100 to 4095, 0 V to V_{REF} range.
Reduced code range of 100 to 3945, 0 V to V_{DD} range.
DAC output load = 10 kΩ and 100 pF.
[11] DAC differential nonlinearity specified on 0 V to V_{REF} and 0 V to V_{DD} ranges.
[12] DAC specification for output impedance in the unbuffered case depends on DAC code.
[13] DAC specifications for I_{SINK}, voltage output settling time, and digital-to-analog glitch energy depend on external buffer implementation in unbuffered mode. DAC in unbuffered mode tested with OP270 external buffer, which has a low input leakage current.
[14] Measured with C_{REF} pin decoupled with 0.47 µF capacitor to ground. Power-up time for the internal reference is determined by the value of the decoupling capacitor chosen for the C_{REF} pin.
[15] When using an external reference device, the internal band gap reference input can be bypassed by setting the ADCCON1.6 bit.
[16] Flash/EE memory reliability characteristics apply to both the Flash/EE program memory and the Flash/EE data memory.
[17] Endurance is qualified to 100,000 cycles as per JEDEC Std. 22 method A117 and measured at –40°C, +25°C, and +85°C. Typical endurance at 25°C is 700,000 cycles.
[18] Retention lifetime equivalent at junction temperature (T_J) = 55°C as per JEDEC Std. 22 method A117. Retention lifetime based on an activation energy of 0.6 eV derates with junction temperature as shown in Figure 38 in the Flash/EE Memory Reliability section.
[19] Power supply current consumption is measured in normal, idle, and power-down modes under the following conditions:

Normal Mode:	Reset = 0.4 V, digital I/O pins = open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), core executing internal software loop.
Idle Mode:	Reset = 0.4 V, digital I/O pins = open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), PCON.0 = 1, core execution suspended in idle mode.
Power-Down Mode:	Reset = 0.4 V, all Port 0 pins = 0.4 V, All other digital I/O and Port 1 pins are open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), PCON.0 = 1, core execution suspended in power-down mode, OSC turned on or off via OSC_PD bit (PLLCON.7) in PLLCON SFR (ADuC842/ADuC843).

[20] DV_{DD} power supply current increases typically by 3 mA (3 V operation) and 10 mA (5 V operation) during a Flash/EE memory program or erase cycle.
[21] Power supply currents are production tested at 5.25 V and 3.3 V for a 5 V and 3 V part, respectively.

Pin No.	Mnemonic	Type[1]	Description
12	DAC1	O	Voltage Output from DAC1. This pin is a no connect on the ADuC843.
13	P1.4/ADC4		Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 4 (ADC4). Channel selection is via ADCCON2 SFR.
14	P1.5/ADC5/$\overline{SS}$	I	Input Port 1 (P1.5). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 5 (ADC5). Channel selection is via ADCCON2 SFR.
			Slave Select Input for the SPI Interface ($\overline{SS}$).
15	P1.3/ADC6	I	Input Port 1 (P1.3). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 6 (ADC6). Channel selection is via ADCCON2 SFR.
16	P1.7/ADC7	I	Input Port 1(P1.7). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 7 (ADC7). Channel selection is via ADCCON2 SFR.
17	RESET	I	Reset. Digital Input. A high level on this pin for 24 master clock cycles while the oscillator is running resets the device.
18	P3.0/RxD	I/O	Input/Output Port 3 (P3.0). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Receiver Data Input (Asynchronous) or Data Input/Output (Synchronous) of the Serial (UART) Port (RxD).
19	P3.1/TxD	I/O	Input/Output Port 3 (P3.1). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Transmitter Data Output (Asynchronous) or Clock Output (Synchronous) of the Serial (UART) Port (TxD).
20	P3.2/$\overline{INT0}$	I/O	Input/Output Port 3 (P3.2). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 0 ($\overline{INT0}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 0.
21	P3.3/$\overline{INT1}$/MISO/PWM1	I/O	Input/Output Port 3 (P3.3). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 1 ($\overline{INT1}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 1.
			SPI Master Input/Slave Output Data I/O Pin for SPI Serial Interface (MISO).
			PWM 1 Voltage Output (PWM1). See the CFG841/CFG842 register for further information.
22, 36, 51	DV_{DD}	P	Digital Positive Supply Voltage. 3 V or 5 V nominal.
23, 37, 38, 50	DGND	G	Digital Ground. DGND is the ground reference point for the digital circuitry.

TERMINOLOGY

ADC SPECIFICATIONS

Integral Nonlinearity

The maximum deviation of any code from a straight line passing through the endpoints of the ADC transfer function. The endpoints of the transfer function are zero scale, a point ½ LSB below the first code transition, and full scale, a point ½ LSB above the last code transition.

Differential Nonlinearity

The difference between the measured and the ideal 1 LSB change between any two adjacent codes in the ADC.

Offset Error

The deviation of the first code transition (0000 . . . 000) to (0000 . . . 001) from the ideal, that is, +½ LSB.

Gain Error

The deviation of the last code transition from the ideal AIN voltage (Full Scale – ½ LSB) after the offset error has been adjusted out.

Signal-to-(Noise + Distortion) Ratio

The measured ratio of signal to (noise + distortion) at the output of the ADC. The signal is the rms amplitude of the fundamental. Noise is the rms sum of all nonfundamental signals up to half the sampling frequency ($f_S/2$), excluding dc. The ratio depends on the number of quantization levels in the digitization process; the more levels, the smaller the quantization noise. The theoretical signal-to-(noise + distortion) ratio for an ideal N-bit converter with a sine wave input is given by

$$Signal\text{-}to\text{-}(Noise + Distortion) = (6.02N + 1.76)\ dB$$

Thus for a 12-bit converter, this is 74 dB.

Total Harmonic Distortion (THD)

The ratio of the rms sum of the harmonics to the fundamental.

DAC SPECIFICATIONS

Relative Accuracy

Relative accuracy or endpoint linearity is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero error and full-scale error.

Voltage Output Settling Time

The amount of time it takes for the output to settle to a specified level for a full-scale input change.

Digital-to-Analog Glitch Impulse

The amount of charge injected into the analog output when the inputs change state. It is specified as the area of the glitch in nV-sec.

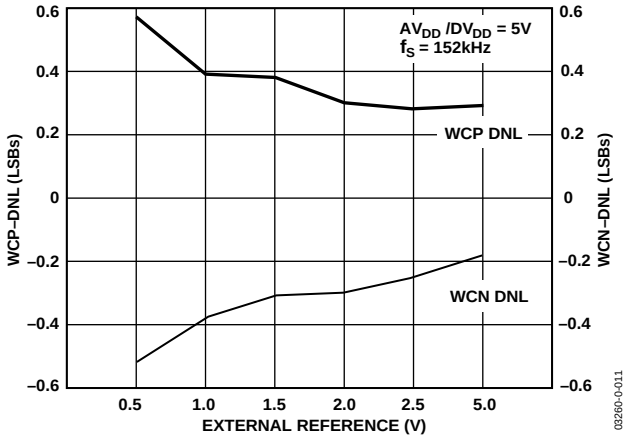

Figure 13. Typical Worst-Case DNL Error vs. V_{REF}, V_{DD} = 5 V

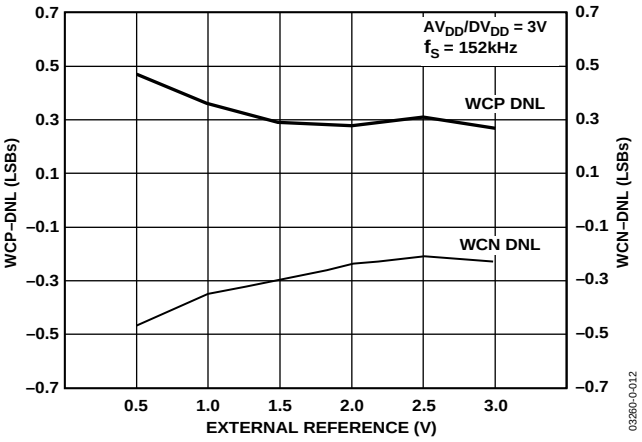

Figure 14. Typical Worst-Case DNL Error vs. V_{REF}, V_{DD} = 3 V

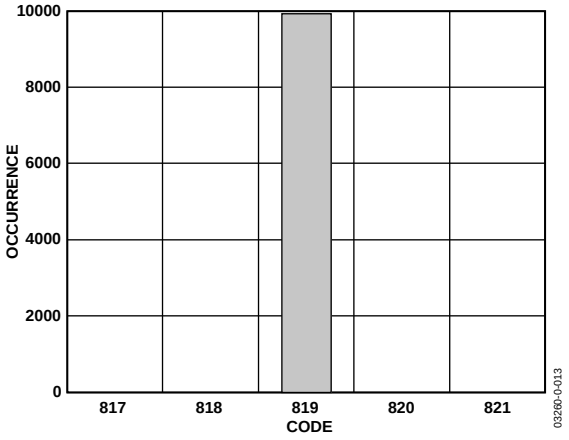

Figure 15. Code Histogram Plot, V_{DD} = 5 V

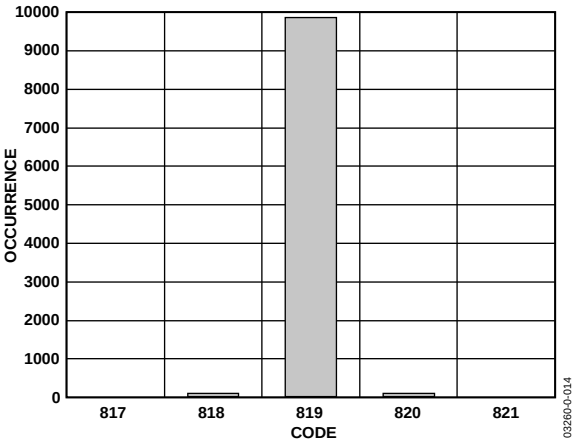

Figure 16. Code Histogram Plot, V_{DD} = 3 V

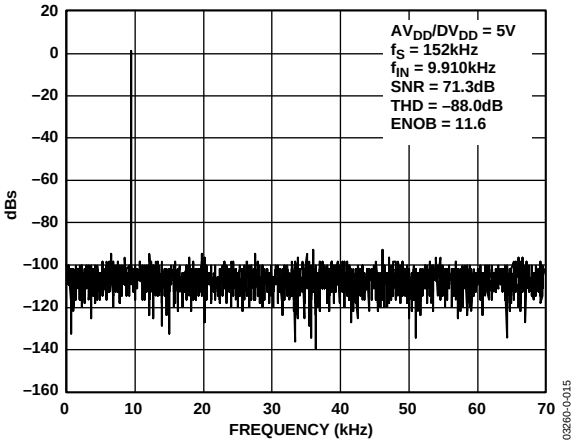

Figure 17. Dynamic Performance at V_{DD} = 5 V

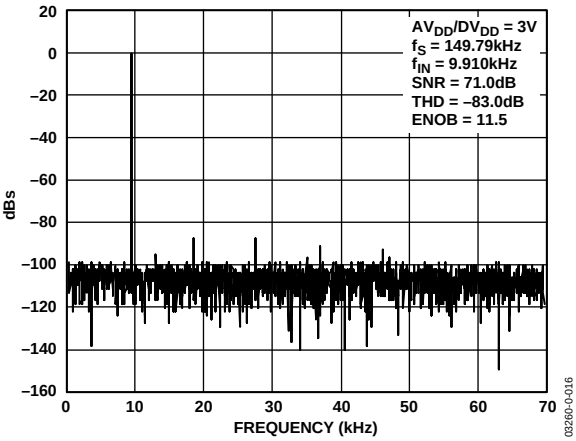

Figure 18. Dynamic Performance at V_{DD} = 3 V

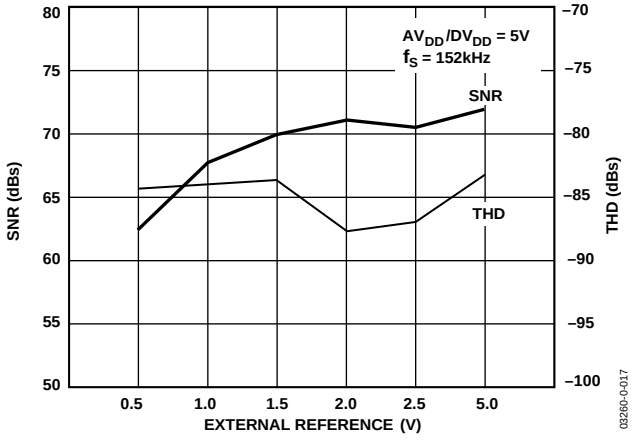

Figure 19. Typical Dynamic Performance vs. V_{REF}, V_{DD} = 5 V

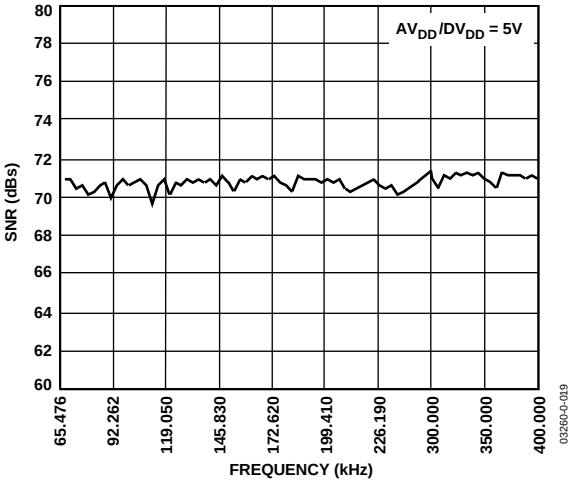

Figure 21. Typical Dynamic Performance vs. Sampling Frequency

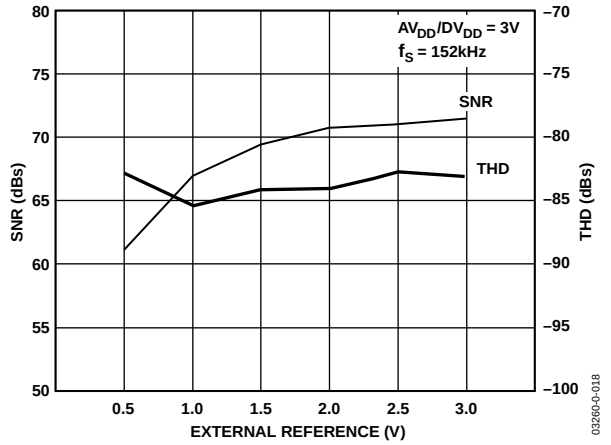

Figure 20. Typical Dynamic Performance vs. V_{REF}, V_{DD} = 3 V

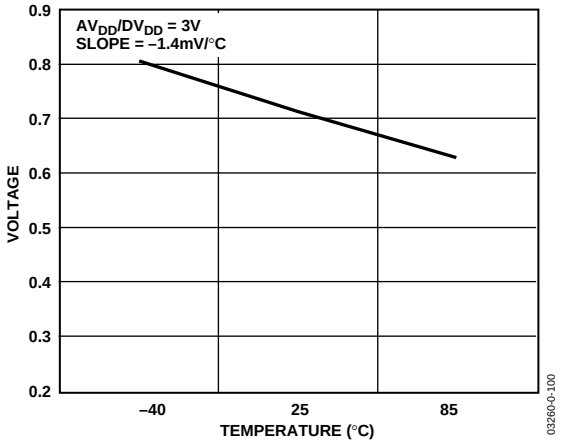

Figure 22. Typical Temperature Sensor Output vs. Temperature

GENERAL DESCRIPTION (*continued*)

The parts also incorporate additional analog functionality with two 12-bit DACs, power supply monitor, and a band gap reference. On-chip digital peripherals include two 16-bit Σ-Δ. DACs, a dual output 16-bit PWM, a watchdog timer, a time interval counter, three timers/counters, and three serial I/O ports (SPI, I²C, and UART).

On the ADuC812 and the ADuC832, the I²C and SPI interfaces share some of the same pins. For backwards compatibility, this is also the case for the ADuC841/ADuC842/ADuC843.

However, there is also the option to allow SPI operate separately on P3.3, P3.4, and P3.5, while I²C uses the standard pins. The I²C interface has also been enhanced to offer repeated start, general call, and quad addressing.

On-chip factory firmware supports in-circuit serial download and debug modes (via UART) as well as single-pin emulation mode via the $\overline{EA}$ pin. A functional block diagram of the parts is shown on the first page.

If using the temperature sensor as the ADC input, the ADC should be configured to use an ADCCLK of MCLK/32 and four acquisition clocks.

Increasing the conversion time on the temperature monitor channel improves the accuracy of the reading. To further improve the accuracy, an external reference with low temperature drift should also be used.

ADC DMA Mode

The on-chip ADC has been designed to run at a maximum conversion speed of 2.38 µs (420 kHz sampling rate). When converting at this rate, the ADuC841/ADuC842/ADuC843 MicroConverter® has 2 µs to read the ADC result and to store the result in memory for further postprocessing; otherwise the next ADC sample could be lost. In an interrupt driven routine, the MicroConverter would also have to jump to the ADC interrupt service routine, which also increases the time required to store the ADC results. In applications where the parts cannot sustain the interrupt rate, an ADC DMA mode is provided.

To enable DMA mode, Bit 6 in ADCCON2 (DMA) must be set, which allows the ADC results to be written directly to a 16 MByte external static memory SRAM (mapped into data memory space) without any interaction from the core of the part. This mode allows the part to capture a contiguous sample stream at full ADC update rates (420 kHz).

Typical DMA Mode Configuration Example

Setting the parts to DMA mode consists of the following steps:

1. The ADC must be powered down. This is done by ensuring that MD1 and MD0 are both set to 0 in ADCCON1.
2. The DMA address pointer must be set to the start address of where the ADC results are to be written. This is done by writing to the DMA mode address pointers DMAL, DMAH, and DMAP. DMAL must be written to first, followed by DMAH, and then by DMAP.
3. The external memory must be preconfigured. This consists of writing the required ADC channel IDs into the top four bits of every second memory location in the external SRAM, starting at the first address specified by the DMA address pointer. Because the ADC DMA mode operates independently from the ADuC841/ADuC842/ADuC843 core, it is necessary to provide it with a stop command. This is done by duplicating the last channel ID to be converted followed by 1111 into the next channel selection field. A typical preconfiguration of external memory is shown in Figure 34.

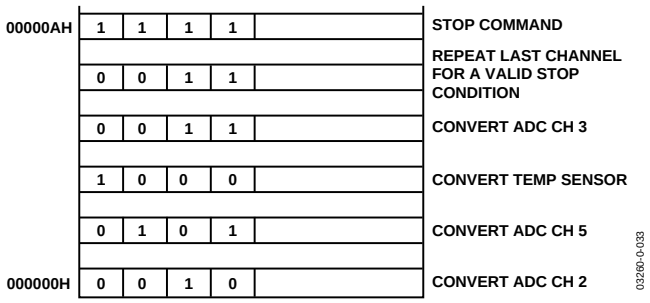

Figure 34. Typical DMA External Memory Preconfiguration

4. The DMA is initiated by writing to the ADC SFRs in the following sequence:
   a. ADCCON2 is written to enable the DMA mode, that is, MOV ADCCON2, #40H; DMA mode enabled.
   b. ADCCON1 is written to configure the conversion time and power-up of the ADC. It can also enable Timer 2 driven conversions or external triggered conversions if required.
   c. ADC conversions are initiated. This is done by starting single conversions, starting Timer 2, running for Timer 2 conversions, or receiving an external trigger.

When the DMA conversions are complete, the ADC interrupt bit, ADCI, is set by hardware, and the external SRAM contains the new ADC conversion results as shown in Figure 35. Note that no result is written to the last two memory locations.

When the DMA mode logic is active, it takes the responsibility of storing the ADC results away from both the user and the core logic of the part. As the DMA interface writes the results of the ADC conversions to external memory, it takes over the external memory interface from the core. Thus, any core instructions that access the external memory while DMA mode is enabled does not get access to the external memory. The core executes the instructions, and they take the same time to execute, but they cannot access the external memory.

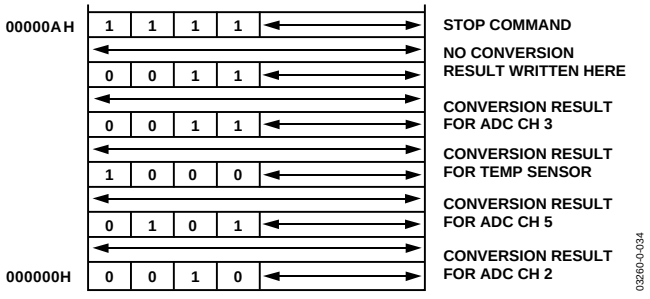

Figure 35. Typical External Memory Configuration Post ADC DMA Operation

Initiating the Calibration in Code

When calibrating the ADC using ADCCON1, the ADC must be set up into the configuration in which it is used. The ADCCON3 register can then be used to set up the device and to calibrate the ADC offset and gain.

```
MOV ADCCON1,#08CH ;   ADC on; ADCCLK set
                      ;to divide by 32,4
                      ;acquisition clock
```

To calibrate device offset:

```
MOV ADCCON2,#0BH      ;select internal AGND
MOV ADCCON3,#25H      ;select offset calibration,
                      ;31 averages per bit,
                      ;offset calibration
```

To calibrate device gain:

```
MOV ADCCON2,#0CH      ;select internal VREF
MOV ADCCON3,#27H      ;select offset calibration,
                      ;31 averages per bit,
                      ;offset calibration
```

To calibrate system offset, connect system AGND to an ADC channel input (0).

```
MOV ADCCON2,#00H      ;select external AGND
MOV ADCCON3,#25H      ;select offset calibration,
                      ;31 averages per bit
```

To calibrate system gain, connect system V_{REF} to an ADC channel input (1).

```
MOV ADCCON2,#01H      ;select external VREF
MOV ADCCON3,#27H      ;select offset calibration,
                      ;31 averages per bit,
                      ;offset calibration
```

The calibration cycle time T_{CAL} is calculated by the following equation:

$$T_{CAL} = 14 \times ADCCLK \times NUMAV \times (16 + T_{ACQ})$$

For an ADCCLK/FCORE divide ratio of 32, T_{ACQ} = 4 ADCCLK, and NUMAV = 15, the calibration cycle time is

$$T_{CAL} = 14 \times (1/524288) \times 15 \times (16 + 4)$$

$$T_{CAL} = 8\ ms$$

In a calibration cycle, the ADC busy flag (Bit 7), instead of framing an individual ADC conversion as in normal mode, goes high at the start of calibration and returns to zero only at the end of the calibration cycle. It can therefore be monitored in code to indicate when the calibration cycle is completed. The following code can be used to monitor the BUSY signal during a calibration cycle:

```
WAIT:
MOV A, ADCCON3          ;move ADCCON3 to A
JB ACC.7, WAIT          ;If Bit 7 is set jump to
                        WAIT else continue
```

NONVOLATILE FLASH/EE MEMORY

The ADuC841/ADuC842/ADuC843 incorporate Flash/EE memory technology on-chip to provide the user with nonvolatile, in-circuit, reprogrammable code and data memory space. Flash/EE memory is a relatively recent type of nonvolatile memory technology, which is based on a single transistor cell architecture. Flash/EE memory combines the flexible in-circuit reprogrammable features of EEPROM with the space efficient/density features of EPROM as shown in Figure 37.

Because Flash/EE technology is based on a single transistor cell architecture, a flash memory array, such as EPROM, can be implemented to achieve the space efficiencies or memory densities required by a given design. Like EEPROM, flash memory can be programmed in-system at a byte level; it must first be erased, the erase being performed in page blocks. Thus, flash memory is often and more correctly referred to as Flash/EE memory.

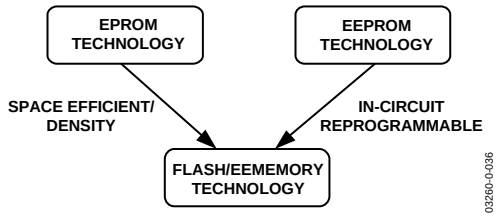

Figure 37. Flash/EE Memory Development

Overall, Flash/EE memory represents a step closer to the ideal memory device that includes nonvolatility, in-circuit programmability, high density, and low cost. Incorporated in the parts, Flash/EE memory technology allows the user to update program code space in-circuit, without the need to replace one-time programmable (OTP) devices at remote operating nodes.

Flash/EE Memory and the ADuC841/ADuC842/ADuC843

The parts provide two arrays of Flash/EE memory for user applications. Up to 62 kBytes of Flash/EE program space are provided on-chip to facilitate code execution without any external discrete ROM device requirements. The program memory can be programmed in-circuit by using the serial download mode provided, by using conventional third party memory programmers, or via a user defined protocol that can configure it as data if required.

Note that the following sections use the 62 kByte program space as an example when referring to ULOAD mode. For the other memory models (32 kByte and 8 kByte), the ULOAD space moves to the top 8 kBytes of the on-chip program memory, that is, for 32 kBytes, the ULOAD space is from 24 kBytes to 32 kBytes, the kernel still resides in a protected space from 60 kBytes to 62 kBytes. There is no ULOAD space present on the 8 kBtye part.

Example: Programming the Flash/EE Data Memory

A user wants to program F3H into the second byte on Page 03H of the Flash/EE data memory space while preserving the other 3 bytes already in this page. A typical program of the Flash/EE data array involves

1. Setting EADRH/L with the page address.
2. Writing the data to be programmed to the EDATA1–4.
3. Writing the ECON SFR with the appropriate command.

Step 1: Set Up the Page Address

Address registers EADRH and EADRL hold the high byte address and the low byte address of the page to be addressed. The assembly language to set up the address may appear as

```
MOV EADRH,#0            ; Set Page Address Pointer
MOV EADRL,#03H
```

Step 2: Set Up the EDATA Registers

Write the four values to be written into the page into the four SFRs, EDATA1–4. Unfortunately, the user does not know three of them. Thus, the user must read the current page and overwrite the second byte.

```
MOV ECON,#1             ; Read Page into EDATA1-4
MOV EDATA2,#0F3H        ; Overwrite byte 2
```

Step 3: Program Page

A byte in the Flash/EE array can be programmed only if it has previously been erased. To be more specific, a byte can be programmed only if it already holds the value FFH. Because of the Flash/EE architecture, this erase must happen at a page level; therefore, a minimum of 4 bytes (1 page) are erased when an erase command is initiated. Once the page is erase, the user can program the 4 bytes in-page and then perform a verification of the data.

```
MOV ECON,#5             ; ERASE Page
MOV ECON,#2             ; WRITE Page
MOV ECON,#4             ; VERIFY Page
MOV A,ECON              ; Check if ECON=0 (OK!)
JNZ ERROR
```

Although the 4 kBytes of Flash/EE data memory are shipped from the factory pre-erased, that is, byte locations set to FFH, it is nonetheless good programming practice to include an ERASEALL routine as part of any configuration/setup code running on the parts. An ERASEALL command consists of writing 06H to the ECON SFR, which initiates an erase of the 4-kByte Flash/EE array. This command coded in 8051 assembly would appear as

```
MOV ECON,#06H           ; Erase all Command
                        ; 2 ms Duration
```

Flash/EE Memory Timing

Typical program and erase times for the parts are as follows:

Normal Mode (operating on Flash/EE data memory)

READPAGE (4 bytes)	22 machine cycles
WRITEPAGE (4 bytes)	380 µs
VERIFYPAGE (4 bytes)	22 machine cycles
ERASEPAGE (4 bytes)	2 ms
ERASEALL (4 kBytes)	2 ms
READBYTE (1 byte)	9 machine cycles
WRITEBYTE (1 byte)	200 µs

ULOAD Mode (operating on Flash/EE program memory)

WRITEPAGE (256 bytes)	16.5 ms
ERASEPAGE (64 bytes)	2 ms
ERASEALL (56 kBytes)	2 ms
WRITEBYTE (1 byte)	200 µs

Note that a given mode of operation is initiated as soon as the command word is written to the ECON SFR. The core microcontroller operation on the parts is idled until the requested program/read or erase mode is completed. In practice, this means that even though the Flash/EE memory mode of operation is typically initiated with a two machine cycle MOV instruction (to write to the ECON SFR), the next instruction is not executed until the Flash/EE operation is complete. This means that the core cannot respond to interrupt requests until the Flash/EE operation is complete, although the core peripheral functions like counter/timers continue to count and time as configured throughout this period.

ON-CHIP PLL

The ADuC842 and ADuC843 are intended for use with a 32.768 kHz watch crystal. A PLL locks onto a multiple (512) of this to provide a stable 16.78 MHz clock for the system. The ADuC841 operates directly from an external crystal. The core can operate at this frequency or at binary submultiples of it to allow power saving in cases where maximum core performance is not required. The default core clock is the PLL clock divided by 8 or 2.097152 MHz. The ADC clocks are also derived from the PLL clock, with the modulator rate being the same as the crystal oscillator frequency. The preceding choice of frequencies ensures that the modulators and the core are synchronous, regardless of the core clock rate. The PLL control register is PLLCON.

At 5 V the core clock can be set to a maximum of 16.78 MHz, while at 3 V the maximum core clock setting is 8.38 MHz. The CD bits should not be set to 0 on a 3 V part.

Note that on the ADuC841, changing the CD bits in PLLCON causes the core speed to change. The core speed is crystal freq/2^{CD}. The other bits in PLLCON are reserved in the case of the ADuC841 and should be written with 0.

PLLCON PLL	**Control Register**
SFR Address	D7H
Power-On Default	53H
Bit Addressable	No

Table 17. PLLCON SFR Bit Designations

Bit No.	Name	Description			
7	OSC_PD	Oscillator Power-Down Bit. Set by the user to halt the 32 kHz oscillator in power-down mode. Cleared by the user to enable the 32 kHz oscillator in power-down mode. This feature allows the TIC to continue counting even in power-down mode.			
6	LOCK	PLL Lock Bit. This is a read-only bit. Set automatically at power-on to indicate that the PLL loop is correctly tracking the crystal clock. If the external crystal subsequently becomes disconnected, the PLL rails. Cleared automatically at power-on to indicate that the PLL is not correctly tracking the crystal clock. This may be due to the absence of a crystal clock or an external crystal at power-on. In this mode, the PLL output can be 16.78 MHz ±20%.			
5	----	Reserved. Should be written with 0.			
4	----	Reserved. Should be written with 0.			
3	FINT	Fast Interrupt Response Bit. Set by the user enabling the response to any interrupt to be executed at the fastest core clock frequency, regardless of the configuration of the CD2–0 bits (see below). Once user code has returned from an interrupt, the core resumes code execution at the core clock selected by the CD2–0 bits. Cleared by the user to disable the fast interrupt response feature.			
2	CD2	CPU (Core Clock) Divider Bits.			
1	CD1	This number determines the frequency at which the microcontroller core operates.			
0	CD0	CD2	CD1	CD0	Core Clock Frequency (MHz)
		0	0	0	16.777216
		0	0	1	8.388608
		0	1	0	4.194304
		0	1	1	2.097152 (Default Core Clock Frequency)
		1	0	0	1.048576
		1	0	1	0.524288
		1	1	0	0.262144
		1	1	1	0.131072

WATCHDOG TIMER

The purpose of the watchdog timer is to generate a device reset or interrupt within a reasonable amount of time if the ADuC841/ADuC842/ADuC843 enter an erroneous state, possibly due to a programming error or electrical noise. The watchdog function can be disabled by clearing the WDE (watchdog enable) bit in the watchdog control (WDCON) SFR. When enabled, the watchdog circuit generates a system reset or interrupt (WDS) if the user program fails to set the watchdog (WDE) bit within a predetermined amount of time (see PRE3-0 bits in Table 24. The watchdog timer is clocked directly from the 32 kHz external crystal on the ADuC842/ADuC843. On the ADuC841, the watchdog timer is clocked by an internal R/C oscillator at 32 kHz ±10%. The WDCON SFR can be written only by user software if the double write sequence described in WDWR below is initiated on every write access to the WDCON SFR.

WDCON Watchdog Timer	Control Register
SFR Address	C0H
Power-On Default	10H
Bit Addressable	Yes

Table 24. WDCON SFR Bit Designations

Bit No.	Name	Description
7	PRE3	Watchdog Timer Prescale Bits.
6	PRE2	The watchdog timeout period is given by the equation $t_{WD} = (2^{PRE} \times (2^9/f_{XTAL}))$
5	PRE1	(0 – PRE – 7; f_{XTAL} = 32.768 kHz (ADuC842/ADuC843), or 32kHz ± 10% (ADuC841))
4	PRE0	PRE3 PRE2 PRE1 PRE0 Timeout Period (ms) Action 0 0 0 0 15.6 Reset or Interrupt 0 0 0 1 31.2 Reset or Interrupt 0 0 1 0 62.5 Reset or Interrupt 0 0 1 1 125 Reset or Interrupt 0 1 0 0 250 Reset or Interrupt 0 1 0 1 500 Reset or Interrupt 0 1 1 0 1000 Reset or Interrupt 0 1 1 1 2000 Reset or Interrupt 1 0 0 0 0.0 Immediate Reset PRE3–0 > 1000 Reserved
3	WDIR	Watchdog Interrupt Response Enable Bit. If this bit is set by the user, the watchdog generates an interrupt response instead of a system reset when the watchdog timeout period has expired. This interrupt is not disabled by the CLR $\overline{EA}$ instruction, and it is also a fixed, high priority interrupt. If the watchdog is not being used to monitor the system, it can be used alternatively as a timer. The prescaler is used to set the timeout period in which an interrupt is generated.
2	WDS	Watchdog Status Bit. Set by the watchdog controller to indicate that a watchdog timeout has occurred. Cleared by writing a 0 or by an external hardware reset. It is not cleared by a watchdog reset.
1	WDE	Watchdog Enable Bit. Set by the user to enable the watchdog and clear its counters. If this bit is not set by the user within the watchdog timeout period, the watchdog generates a reset or interrupt, depending on WDIR. Cleared under the following conditions: user writes 0, watchdog reset (WDIR = 0); hardware reset; PSM interrupt.

0	WDWR	Watchdog Write Enable Bit.
		To write data to the WDCON SFR involves a double instruction sequence. The WDWR bit must be set and the very next instruction must be a write instruction to the WDCON SFR.
		For example:
		`CLR EA ;disable interrupts while writing`
		`;to WDT`
		`SETB WDWR ;allow write to WDCON`
		`MOV WDCON,#72H ;enable WDT for 2.0s timeout`
		`SETB EA ;enable interrupts again (if rqd)`

MOSI is shared with P3.3 and, as such, has the same configuration as the one shown in Figure 61.

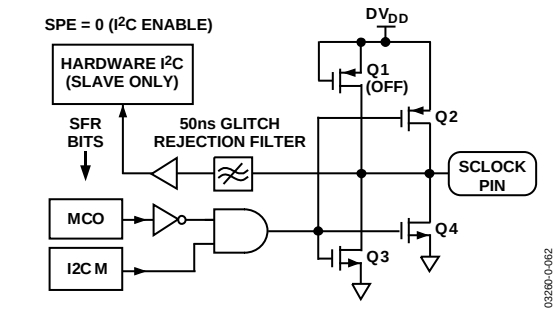

Figure 63. SCLOCK Pin I/O Functional Equivalent in I²C Mode

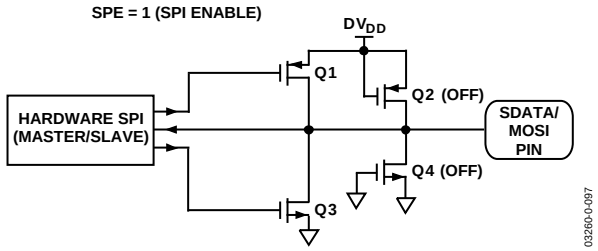

Figure 64. SDATA/MOSI Pin I/O Functional Equivalent in SPI Mode

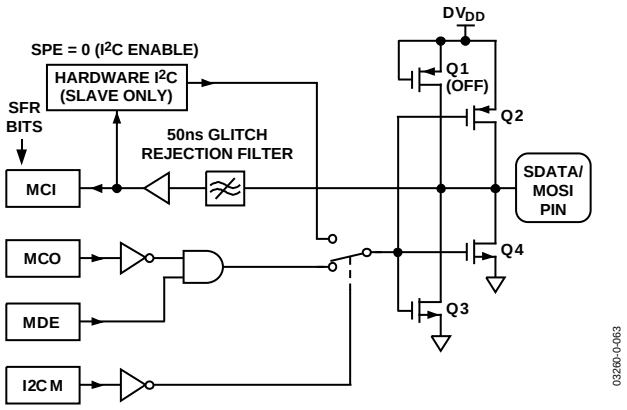

Figure 65. SDATA/MOSI Pin I/O Functional Equivalent in I²C Mode

Read-Modify-Write Instructions

Some 8051 instructions that read a port read the latch while others read the pin. The instructions that read the latch rather than the pins are the ones that read a value, possibly change it, and then rewrite it to the latch. These are called read-modify-write instructions, which are listed below. When the destination operand is a port or a port bit, these instructions read the latch rather than the pin.

Table 28. Read-Write-Modify Instructions

Instruction	Description
ANL	Logical AND, for example, ANL P1, A
ORL	(Logical OR, for example, ORL P2, A
XRL	(Logical EX-OR, for example, XRL P3, A
JBC	Jump if Bit = 1 and clear bit, for example, JBC P1.1, LABEL
CPL	Complement bit, for example, CPL P3.0
INC	Increment, for example, INC P2
DEC	Decrement, for example, DEC P2
DJNZ	Decrement and Jump if Not Zero, for example, DJNZ P3, LABEL
MOV PX.Y, C[1]	Move Carry to Bit Y of Port X
CLR PX.Y[1]	Clear Bit Y of Port X
SETB PX.Y[1]	Set Bit Y of Port X

[1] These instructions read the port byte (all 8 bits), modify the addressed bit, and then write the new byte back to the latch.

Read-modify-write instructions are directed to the latch rather than to the pin to avoid a possible misinterpretation of the voltage level of a pin. For example, a port pin might be used to drive the base of a transistor. When 1 is written to the bit, the transistor is turned on. If the CPU then reads the same port bit at the pin rather than the latch, it reads the base voltage of the transistor and interprets it as a Logic 0. Reading the latch rather than the pin returns the correct value of 1.

Timers/Counters

The ADuC841/ADuC842/ADuC843 have three 16-bit timer/counters: Timer 0, Timer 1, and Timer 2. The timer/counter hardware is included on-chip to relieve the processor core of the overhead inherent in implementing timer/counter functionality in software. Each timer/counter consists of two 8-bit registers: THx and TLx (x = 0, 1, and 2). All three can be configured to operate either as timers or as event counters.

In timer function, the TLx register is incremented every machine cycle. Thus, one can think of it as counting machine cycles. Since a machine cycle on a single-cycle core consists of one core clock period, the maximum count rate is the core clock frequency.

In counter function, the TLx register is incremented by a 1-to-0 transition at its corresponding external input pin: T0, T1, or T2. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. Since it takes two machine cycles (two core clock periods) to recognize a 1-to-0 transition, the maximum count rate is half the core clock frequency.

There are no restrictions on the duty cycle of the external input signal, but to ensure that a given level is sampled at least once before it changes, it must be held for a minimum of one full machine cycle. User configuration and control of all timer operating modes is achieved via three SFRs:

TMOD, TCON	Control and configuration for Timers 0 and 1.
T2CON	Control and configuration for Timer 2.
TMOD	Timer/Counter 0 and 1 Mode Register
SFR Address	89H
Power-On Default	00H
Bit Addressable	No

Table 29. TMOD SFR Bit Designations

Bit No.	Name	Description
7	Gate	Timer 1 Gating Control. Set by software to enable Timer/Counter 1 only while the $\overline{INT1}$ pin is high and the TR1 control bit is set. Cleared by software to enable Timer 1 whenever the TR1 control bit is set.
6	C/T	Timer 1 Timer or Counter Select Bit. Set by software to select counter operation (input from T1 pin). Cleared by software to select timer operation (input from internal system clock).
5	M1	Timer 1 Mode Select Bit 1 (Used with M0 Bit).
4	M0	Timer 1 Mode Select Bit 0. M1 M0 0 0 TH1 operates as an 8-bit timer/counter. TL1 serves as 5-bit prescaler. 0 1 16-Bit Timer/Counter. TH1 and TL1 are cascaded; there is no prescaler. 1 0 8-Bit Autoreload Timer/Counter. TH1 holds a value that is to be reloaded into TL1 each time it overflows. 1 1 Timer/Counter 1 Stopped.
3	Gate	Timer 0 Gating Control. Set by software to enable Timer/Counter 0 only while the $\overline{INT0}$ pin is high and the TR0 control bit is set. Cleared by software to enable Timer 0 whenever the TR0 control bit is set.
2	C/T	Timer 0 Timer or Counter Select Bit. Set by software to select counter operation (input from T0 pin). Cleared by software to select timer operation (input from internal system clock).
1	M1	Timer 0 Mode Select Bit 1.
0	M0	Timer 0 Mode Select Bit 0. M1 M0 0 0 TH0 operates as an 8-bit timer/counter. TL0 serves as a 5-bit prescaler. 0 1 16-Bit Timer/Counter. TH0 and TL0 are cascaded; there is no prescaler. 1 0 8-Bit Autoreload Timer/Counter. TH0 holds a value that is to be reloaded into TL0 each time it overflows. 1 1 TL0 is an 8-bit timer/counter controlled by the standard Timer 0 control bits. TH0 is an 8-bit timer only, controlled by Timer 1 control bits.

Mode 3: 9-Bit UART with Variable Baud Rate

Mode 3 is selected by setting both SM0 and SM1. In this mode, the 8051 UART serial port operates in 9-bit mode with a variable baud rate determined by either Timer 1 or Timer 2. The operation of the 9-bit UART is the same as for Mode 2, but the baud rate can be varied as for Mode 1.

In all four modes, transmission is initiated by any instruction that uses SBUF as a destination register. Reception is initiated in Mode 0 by the condition RI = 0 and REN = 1. Reception is initiated in the other modes by the incoming start bit if REN = 1.

UART Serial Port Baud Rate Generation

Mode 0 Baud Rate Generation

The baud rate in Mode 0 is fixed.

Mode 0 Baud Rate = (*Core Clock Frequency*/12)

Mode 2 Baud Rate Generation

The baud rate in Mode 2 depends on the value of the SMOD bit in the PCON SFR. If SMOD = 0, the baud rate is 1/32 of the core clock. If SMOD = 1, the baud rate is 1/16 of the core clock:

Mode 2 Baud Rate = (2^{SMOD}/32 × [*Core Clock Frequency*])

Modes 1 and 3 Baud Rate Generation

The baud rates in Modes 1 and 3 are determined by the overflow rate in Timer 1 or Timer 2, or in both (one for transmit and the other for receive).

Timer 1 Generated Baud Rates

When Timer 1 is used as the baud rate generator, the baud rates in Modes 1 and 3 are determined by the Timer 1 overflow rate and the value of SMOD as follows:

Modes 1 and 3 Baud Rate = (2^{SMOD}/32 × (*Timer 1 Overflow Rate*)

The Timer 1 interrupt should be disabled in this application. The timer itself can be configured for either timer or counter operation, and in any of its three running modes. In the most typical application, it is configured for timer operation in the autoreload mode (high nibble of TMOD = 0010 binary). In that case, the baud rate is given by the formula

Modes 1 and 3 Baud Rate =
(2^{SMOD}/32) × (*Core Clock*/ [256 − *TH1*])

Timer 2 Generated Baud Rates

Baud rates can also be generated using Timer 2. Using Timer 2 is similar to using Timer 1 in that the timer must overflow 16 times before a bit is transmitted/received. Because Timer 2 has a 16-bit autoreload mode, a wider range of baud rates is possible using Timer 2.

Modes 1 and 2 Baud Rate = (1/16) × (*Timer 2 Overflow Rate*)

Therefore, when Timer 2 is used to generate baud rates, the timer increments every two clock cycles rather than every core machine cycle as before. Thus, it increments six times faster than Timer 1, and therefore baud rates six times faster are possible. Because Timer 2 has 16-bit autoreload capability, very low baud rates are still possible.

Timer 2 is selected as the baud rate generator by setting the TCLK and/or RCLK in T2CON. The baud rates for transmit and receive can be simultaneously different. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode as shown in Figure 73.

In this case, the baud rate is given by the formula

Modes 1 and 3 Baud Rate =
(*Core Clock*)/(16 × [65536 − (*RCAP 2H, RCAP 2L*)])

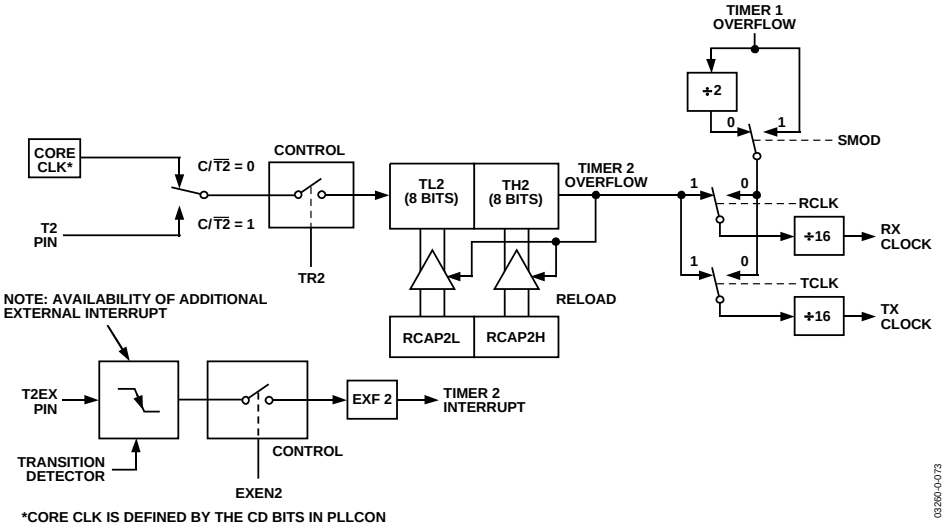

Figure 73. Timer 2, UART Baud Rates

INTERRUPT SYSTEM

The ADuC841/ADuC842/ADuC843 provide a total of nine interrupt sources with two priority levels. The control and configuration of the interrupt system is carried out through three interrupt-related SFRs:

IE	Interrupt Enable Register
IP	Interrupt Priority Register
IEIP2	Secondary Interrupt Enable Register

IE	**Interrupt Enable Register**
SFR Address	A8H
Power-On Default	00H
Bit Addressable	Yes

Table 36. IE SFR Bit Designations

Bit No.	Name	Description
7	EA	Set by the user to enable, or cleared to disable all interrupt sources.
6	EADC	Set by the user to enable, or cleared to disable ADC interrupts.
5	ET2	Set by the user to enable, or cleared to disable Timer 2 interrupts.
4	ES	Set by the user to enable, or cleared to disable UART serial port interrupts.
3	ET1	Set by the user to enable, or cleared to disable 0 Timer 1 interrupts.
2	EX1	Set by the user to enable, or cleared to disable External Interrupt 1.
1	ET0	Set by the user to enable, or cleared to disable Timer 0 interrupts.
0	EX0	Set by the user to enable, or cleared to disable External Interrupt 0 .

IP	**Interrupt Priority Register**
SFR Address	B8H
Power-On Default	00H
Bit Addressable	Yes

Table 37. IP SFR Bit Designations

Bit No.	Name	Description
7	----	Reserved.
6	PADC	Written by the user to select the ADC interrupt priority (1 = High; 0 = Low).
5	PT2	Written by the user to select the Timer 2 interrupt priority (1 = High; 0 = Low).
4	PS	Written by the user to select the UART serial port interrupt priority (1 = High; 0 = Low).
3	PT1	Written by the user to select the Timer 1 interrupt priority (1 = High; 0 = Low).
2	PX1	Written by the user to select External Interrupt 1 priority (1 = High; 0 = Low).
1	PT0	Written by the user to select the Timer 0 interrupt priority (1 = High; 0 = Low).
0	PX0	Written by the user to select External Interrupt 0 priority (1 = High; 0 = Low).

IEIP2	Secondary Interrupt Enable Register
SFR Address	A9H
Power-On Default	A0H
Bit Addressable	No

Table 38. IEIP2 SFR Bit Designations

Bit No.	Name	Description
7	----	Reserved.
6	PTI	Priority for time interval interrupt.
5	PPSM	Priority for power supply monitor interrupt.
4	PSI	Priority for SPI/I²C interrupt.
3	----	This bit must contain zero.
2	ETI	Set by the user to enable, or cleared to disable time interval counter interrupts.
1	EPSMI	Set by the user to enable, or cleared to disable power supply monitor interrupts.
0	ESI	Set by the user to enable, or cleared to disable SPI or I²C serial port interrupts.

Interrupt Priority

The interrupt enable registers are written by the user to enable individual interrupt sources, while the interrupt priority registers allow the user to select one of two priority levels for each interrupt. An interrupt of a high priority may interrupt the service routine of a low priority interrupt, and if two interrupts of different priority occur at the same time, the higher level interrupt is serviced first. An interrupt cannot be interrupted by another interrupt of the same priority level. If two interrupts of the same priority level occur simultaneously, a polling sequence is observed as shown in Table 39.

Table 39. Priority within an Interrupt Level

Source	Priority	Description
PSMI	1 (Highest)	Power Supply Monitor Interrupt.
WDS	2	Watchdog Timer Interrupt.
IE0	2	External Interrupt 0.
ADCI	3	ADC Interrupt.
TF0	4	Timer/Counter 0 Interrupt.
IE1	5	External Interrupt 1.
TF1	6	Timer/Counter 1 Interrupt.
ISPI/I2CI	7	SPI Interrupt/I²C Interrupt.
RI + TI	8	Serial Interrupt.
TF2 + EXF2	9	Timer/Counter 2 Interrupt.
TII	11(Lowest)	Time Interval Counter Interrupt.

Interrupt Vectors

When an interrupt occurs, the program counter is pushed onto the stack, and the corresponding interrupt vector address is loaded into the program counter. The interrupt vector addresses are shown in Table 40.

Table 40. Interrupt Vector Addresses

Source	Vector Address
IE0	0003H
TF0	000BH
IE1	0013H
TF1	001BH
RI + TI	0023H
TF2 + EXF2	002BH
ADCI	0033H
ISPI/I2CI	003BH
PSMI	0043H
TII	0053H
WDS	005BH

HARDWARE DESIGN CONSIDERATIONS

This section outlines some of the key hardware design considerations that must be addressed when integrating the ADuC841/ADuC842/ADuC843 into any hardware system.

Clock Oscillator

The clock source for the parts can be generated by the internal PLL or by an external clock input. To use the internal PLL, connect a 32.768 kHz parallel resonant crystal between XTAL1 and XTAL2, and connect a capacitor from each pin to ground as shown in Figure 75. The parts contain an internal capacitance of 18 pF on the XTAL1 and XTAL2 pins, which is sufficient for most watch crystals. This crystal allows the PLL to lock correctly to give an f_{VCO} of 16.777216 MHz. If no crystal is present, the PLL free runs, giving an fVCO of 16.7 MHz ±20%. In this mode, the CD bits are limited to CD = 1, giving a max core clock of 8.38 MHz. This is useful if an external clock input is required. The part powers up and the PLL free runs; the user then writes to the CFG842 SFR in software to enable the external clock input on P3.4. Note that double the required clock must be provided externally since the part runs at CD = 1. A better solution is to use the ADuC841 with the external clock.

For the ADuC841, connect the crystal in the same manner; external capacitors should be connected as per the crystal manufacturer's recommendations. A minimum capacitance of 20 pF is recommended on XTAL1 and XTAL2. The ADuC841 does not operate if no crystal is present.

An external clock may be connected as shown in Figure 76 and Figure 77.

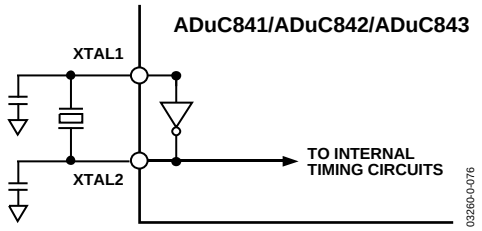

Figure 75. External Parallel Resonant Crystal Connections

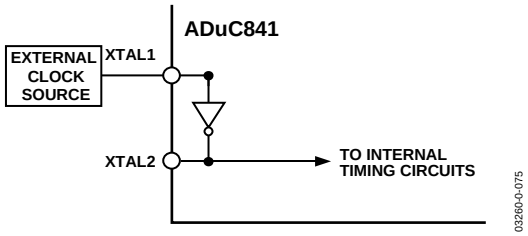

Figure 76. Connecting an External Clock Source (ADuC841)

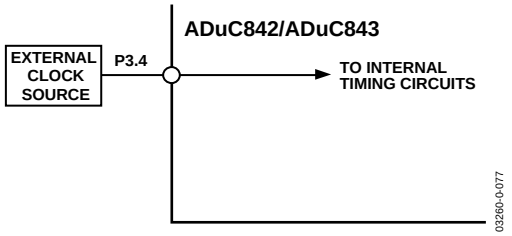

Figure 77. Connecting an External Clock Source (ADuC842/ADuC843)

Whether using the internal PLL or an external clock source, the specified operational clock speed range of the devices is 400 kHz to 16.777216 MHz, (20 MHz, ADuC841). The core itself is static, and functions all the way down to dc. But at clock speeds slower that 400 kHz, the ADC can no longer function correctly. Therefore, to ensure specified operation, use a clock frequency of at least 400 kHz and no more than 20 MHz.

External Memory Interface

In addition to its internal program and data memories, the parts can access up to 16 MBytes of external data memory (SRAM). Note that the parts cannot access external program memory.

Figure 78 shows a hardware configuration for accessing up to 64 kBytes of external RAM. This interface is standard to any 8051 compatible MCU.

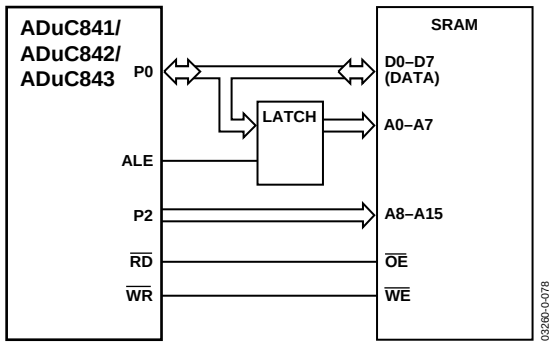

Figure 78. External Data Memory Interface (64 kBytes Address Space)

Parameter		16 MHz Core Clk		8 MHz Core Clock		
EXTERNAL DATA MEMORY WRITE CYCLE		**Min**	**Max**	**Min**	**Max**	**Unit**
t_{WLWH}	$\overline{WR}$ Pulse Width	65		130		ns
t_{AVLL}	Address Valid after ALE Low	60		120		ns
t_{LLAX}	Address Hold after ALE Low	65		135		ns
t_{LLWL}	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low		130		260	ns
t_{AVWL}	Address Valid to $\overline{RD}$ or $\overline{WR}$ Low	190		375		ns
t_{QVWX}	Data Valid to $\overline{WR}$ Transition	60		120		ns
t_{QVWH}	Data Setup before $\overline{WR}$	120		250		ns
t_{WHQX}	Data and Address Hold after $\overline{WR}$	380		755		ns
t_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE High	60		125		ns

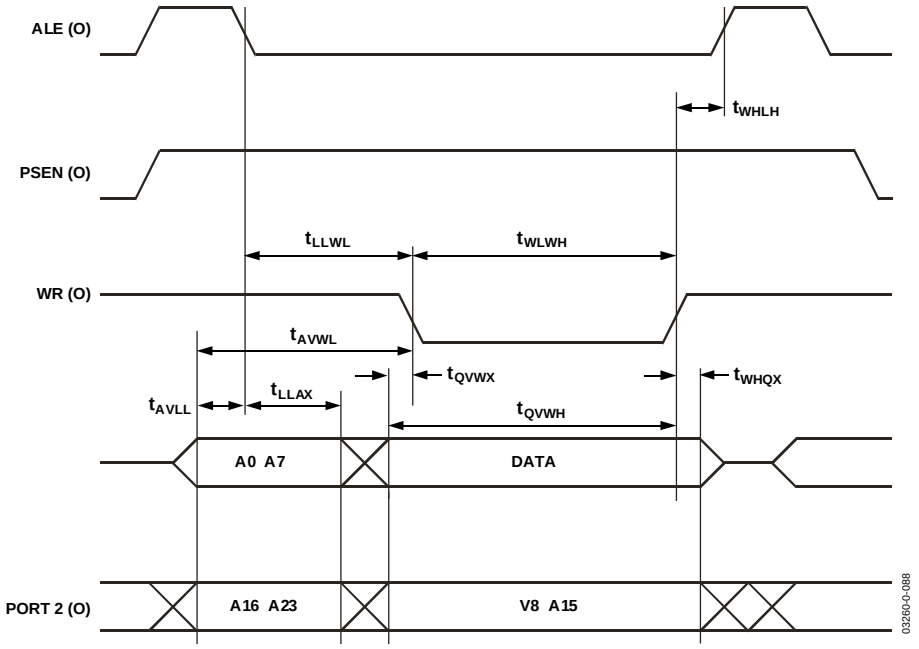

Figure 89. External Data Memory Write Cycle

Parameter	SPI MASTER MODE TIMING (CPHA = 1)	Min	Typ	Max	Unit
t_{SL}	SCLOCK Low Pulse Width[1]		476		ns
t_{SH}	SCLOCK High Pulse Width[1]		476		ns
t_{DAV}	Data Output Valid after SCLOCK Edge			50	ns
t_{DSU}	Data Input Setup Time before SCLOCK Edge	100			ns
t_{DHD}	Data Input Hold Time after SCLOCK Edge	100			ns
t_{DF}	Data Output Fall Time		10	25	ns
t_{DR}	Data Output Rise Time		10	25	ns
t_{SR}	SCLOCK Rise Time		10	25	ns
t_{SF}	SCLOCK Fall Time		10	25	ns

[1] Characterized under the following conditions:
a. Core clock divider bits CD2, CD1, and CD0 bits in PLLCON SFR set to 0, 1, and 1, respectively, that is, core clock frequency = 2.09 MHz.
b. SPI bit-rate selection bits SPR1 and SPR0 in SPICON SFR set to 0 and 0, respectively.

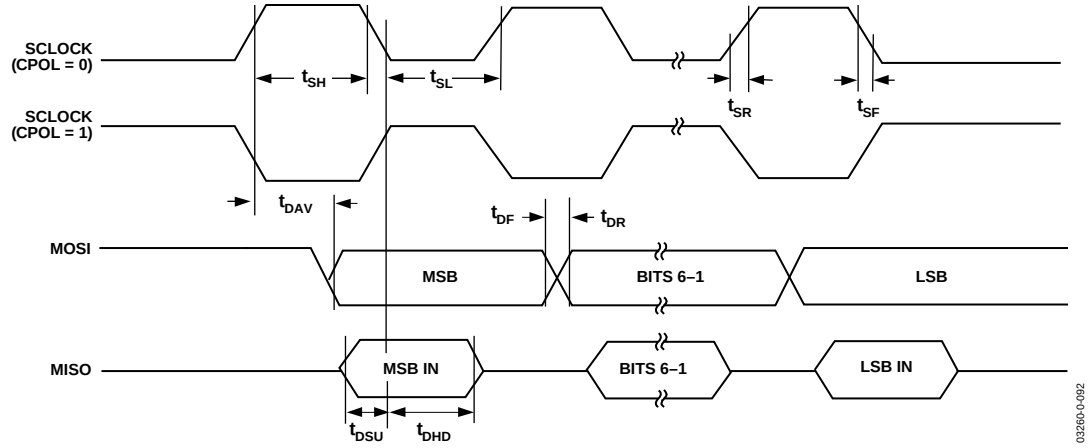

Figure 91. SPI Master Mode Timing (CPHA = 1)

OUTLINE DIMENSIONS

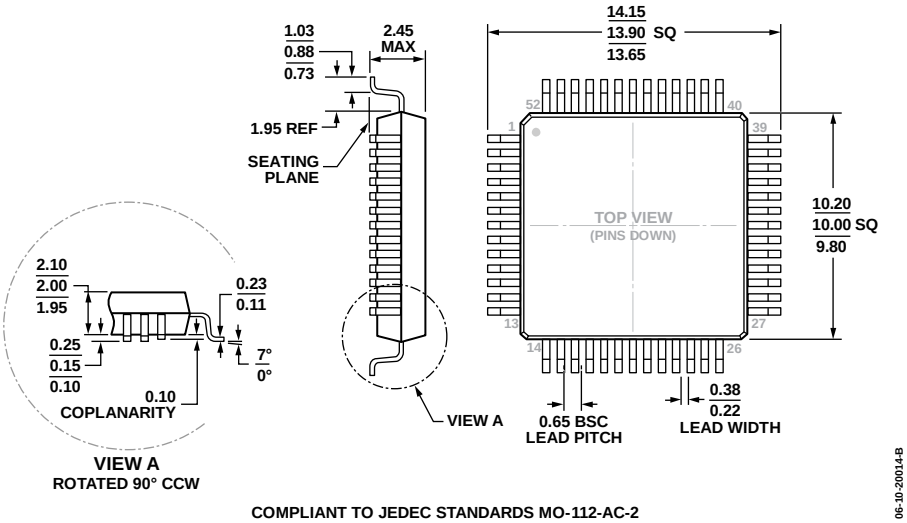

Figure 95. 52-Lead Plastic Quad Flat Package [MQFP]
(S-52-2)
Dimensions shown in millimeters

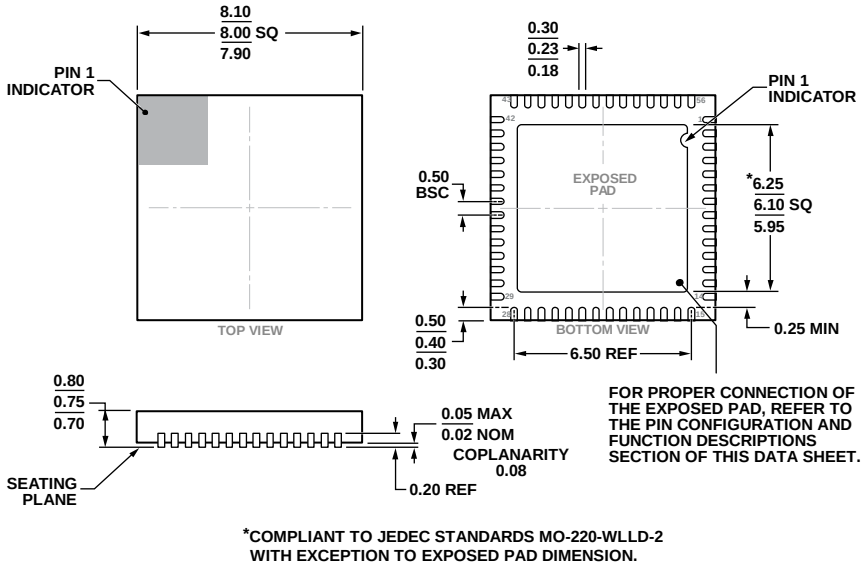

Figure 96. 56-Lead Frame Chip Scale Package [LFCSP]
8 mm × 8 mm and 0.75 mm Package Height
(CP-56-11)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1]	Supply Voltage V_{DD}	User Program Code Space	Temperature Range	Package Description	Package Option
ADuC841BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC841BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC841BCPZ62-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC842BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC842BCPZ62-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ32-5	5	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ32-3	3	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADUC843BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC843BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC843BCP62Z-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCP32Z-5	5	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ32-3	3	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
EVAL-ADuC841QSZ	5			QuickStart Development System for the ADuC841	
EVAL-ADuC841QSPZ	5			QuickStart Plus Development System	
EVAL-ADuC842QSZ	5			QuickStart Development System for the ADuC842 and ADuC843	
EVAL-ADuC842QSPZ	5			QuickStart Plus Development System	
USB-EA-CONVZ				USB to EA Emulator	

[1] The only difference between the ADuC842 and ADuC843devices is the voltage output DACs on the ADuC842; thus, the evaluation system for the ADuC842 is also suitable for the ADuC843.

I²C refers to a communications protocol originally developed by Philips Semiconductors (now NXP Semiconductors).

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